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HARTING DIN Signal female connector RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. drilled hole Ø finished hole Ø plating (e.g. Sn) Cu min. 25 µm <table><tr><td rowspan="2">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Sn plated hole Ø</td><td>max. 15 µm 0,94 – 1,09 mm</td></tr><tr><td rowspan="2">Chemical tin plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Sn plated hole Ø</td><td>min. 0,8µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="3">Gold /Nickel plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Ni</td><td>3 – 7 µm</td></tr><tr><td>Au plated hole Ø</td><td>0,05 – 0,12 µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="2">Silver plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Ag plated hole Ø</td><td>0,1 – 0,3 µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="2">Copper plated PCB (OSP)</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15±0,025 mm	Sn plated hole Ø	max. 15 µm 0,94 – 1,09 mm	Chemical tin plated PCB	Drilled hole Ø	1,15±0,025 mm	Sn plated hole Ø	min. 0,8µm 1,00 – 1,10 mm	Gold /Nickel plated PCB	Drilled hole Ø	1,15±0,025 mm	Ni	3 – 7 µm	Au plated hole Ø	0,05 – 0,12 µm 1,00 – 1,10 mm	Silver plated PCB	Drilled hole Ø	1,15±0,025 mm	Ag plated hole Ø	0,1 – 0,3 µm 1,00 – 1,10 mm	Copper plated PCB (OSP)	Drilled hole Ø	1,15±0,025 mm	plated hole Ø	1,00 – 1,10 mm																																																		
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HARTING All rights reserved Department EC PD – DE HARTING Electronics GmbH D-32339 Espelkamp				Scale 1:1 Free size tol. Created by LEHNERT Inspected by ZWAHR Standardisation HOFFMANN Date 2016-11-03 State Final Release DIN Signale female connector Doc-Key / ECM-Nr. 100572187/UGD/001/B 500000111021 Type DS Number 09032100001 Rev. B Page 1/1																																																																																
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